# **Silicon Hot-Carrier Diodes**

# **Schottky Barrier Diodes**

These devices are designed primarily for high–efficiency UHF and VHF detector applications. They are readily adaptable to many other fast switching RF and digital applications. They are supplied in an inexpensive plastic package for low–cost, high–volume consumer and industrial/commercial requirements. They are also available in a Surface Mount package.

#### Features

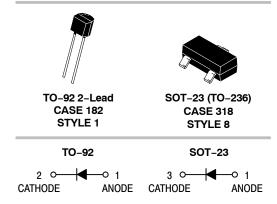
- Extremely Low Minority Carrier Lifetime 15 ps (Typ)
- Very Low Capacitance 1.5 pF (Max) @  $V_R$  = 15 V
- Low Reverse Leakage  $I_R = 13$  nAdc (Typ) MBD301, MMBD301
- S Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q101 Qualified and PPAP Capable
- These Devices are Pb–Free, Halogen Free/BFR Free and are RoHS Compliant



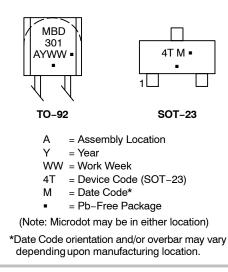
## **ON Semiconductor®**

http://onsemi.com

30 VOLTS SILICON HOT-CARRIER DETECTOR AND SWITCHING DIODES



#### MARKING DIAGRAMS



#### **ORDERING INFORMATION**

See detailed ordering and shipping information in the package dimensions section on page 2 of this data sheet.

#### MAXIMUM RATINGS

Rating	Symbol	Value	Unit
Reverse Voltage	V <sub>R</sub>	30	V
Forward Current (DC)	١ <sub>F</sub>	200 (Max)	mA
Total Device Dissipation @ T <sub>A</sub> = 25°C MBD301G MMBD301LT1G, MMBD301LT3G, SMMBD301LT3G Derate above 25°C MBD301G	PF	280 200 2.8	MW mW/°C
MMBD301LT1G, MMBD301LT3G, SMMBD301LT3G		2.0	
Operating Junction Temperature Range	TJ	–55 to +125	°C
Storage Temperature Range	T <sub>stg</sub>	–55 to +150	°C

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

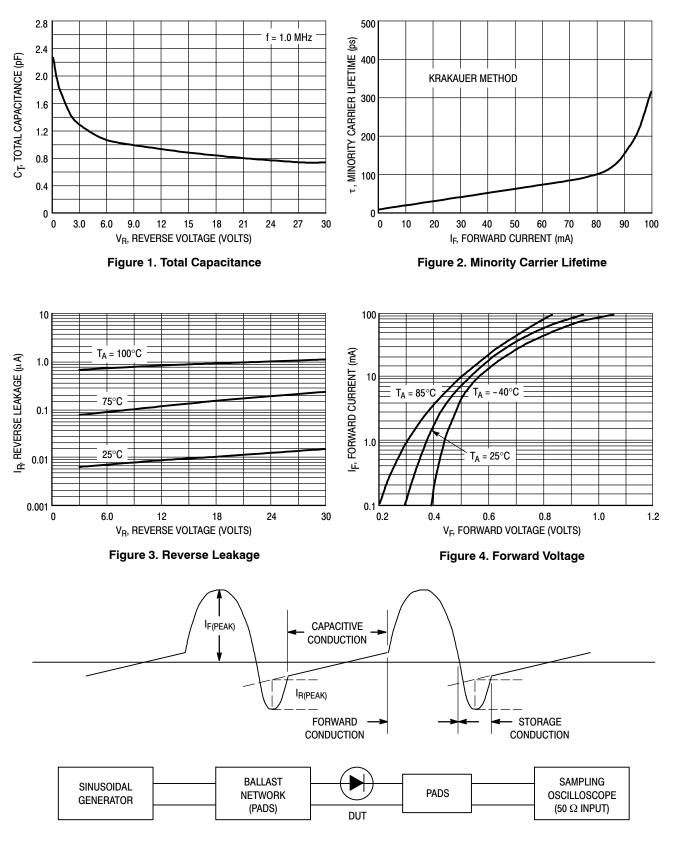
### **ELECTRICAL CHARACTERISTICS** (T<sub>A</sub> = 25°C unless otherwise noted)

Characteristic	Symbol	Min	Тур	Max	Unit
Reverse Breakdown Voltage $(I_R = 10 \ \mu A)$	V <sub>(BR)R</sub>	30	-	-	V
Total Capacitance $(V_R = 15 \text{ V}, \text{ f} = 1.0 \text{ MHz})$ Figure 1	CT	-	0.9	1.5	pF
Reverse Leakage $(V_R = 25 \text{ V})$ Figure 3	I <sub>R</sub>	-	13	200	nAdc
Forward Voltage (I <sub>F</sub> = 1.0 mAdc) Figure 4	V <sub>F</sub>	-	0.38	0.45	Vdc
Forward Voltage (I <sub>F</sub> = 10 mAdc) Figure 4	V <sub>F</sub>	-	0.52	0.6	Vdc

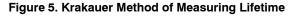
#### ORDERING INFORMATION

Device	Package	Shipping <sup>†</sup>
MBD301G	TO-92 (Pb-Free)	5,000 Units / Bulk
MMBD301LT1G	SOT-23 (Pb-Free)	3,000 / Tape & Reel
MMBD301LT3G	SOT-23 (Pb-Free)	10,000 / Tape & Reel
SMMBD301LT3G	SOT-23 (Pb-Free)	10,000 / Tape & Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

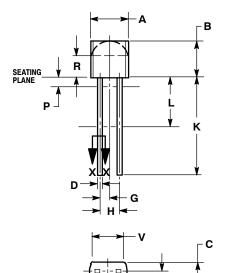


### **TYPICAL ELECTRICAL CHARACTERISTICS**



## PACKAGE DIMENSIONS

TO-92 (TO-226AC) CASE 182-06 ISSUE L



2 Ν Ν





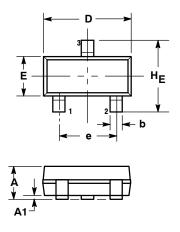
NOTES: 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982. 2. CONTROLLING DIMENSION: INCH. 3. CONTOUR OF PACKAGE BEYOND ZONE R IS UNCONTROLLED. 4. LEAD DIMENSION IS UNCONTROLLED IN P AND BEYOND DIMENSION K MINIMUM.

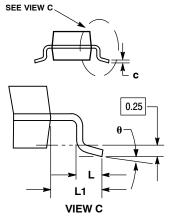
	INCHES		MILLIN	IETERS	
DIM	MIN MAX		MIN	MAX	
Α	0.175	0.205	4.45	5.21	
В	0.170	0.210	4.32	5.33	
С	0.125	0.165	3.18	4.19	
D	0.016	0.021	0.407	0.533	
G	0.050 BSC		1.27 BSC		
н	0.100 BSC		2.54 BSC		
J	0.014	0.016	0.36 0.4		
Κ	0.500		12.70		
L	0.250		6.35		
Ν	0.080	0.105	2.03	2.66	
Р		0.050		1.27	
R	0.115		2.93		
V	0.135		3.43		

STYLE 1: PIN 1. ANODE 2. CATHODE

#### PACKAGE DIMENSIONS

SOT-23 (TO-236) CASE 318-08 ISSUE AP





NOTES

- DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982. 2
- CONTROLLING DIMENSION: INCH. MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH З. THICKNESS. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF BASE MATERIAL.
- DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR GATE BURRS. 4

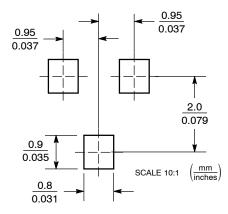
	MILLIMETERS			INCHES		
DIM	MIN	NOM	MAX	MIN	NOM	MAX
Α	0.89	1.00	1.11	0.035	0.040	0.044
A1	0.01	0.06	0.10	0.001	0.002	0.004
b	0.37	0.44	0.50	0.015	0.018	0.020
С	0.09	0.13	0.18	0.003	0.005	0.007
D	2.80	2.90	3.04	0.110	0.114	0.120
E	1.20	1.30	1.40	0.047	0.051	0.055
е	1.78	1.90	2.04	0.070	0.075	0.081
L	0.10	0.20	0.30	0.004	0.008	0.012
L1	0.35	0.54	0.69	0.014	0.021	0.029
HE	2.10	2.40	2.64	0.083	0.094	0.104
θ	0°		10°	0°		10°

STYLE 8:

ANODE PIN 1. 2. NO CONNECTION

3. CATHODE

#### **SOLDERING FOOTPRINT\***



\*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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